

Title (en)

HEAT TRANSFER ELEMENT FOR THERMAL CONTROLS

Title (de)

WÄRMEÜBERTRAGUNGSELEMENT FÜR THERMISCHE STEUERUNGEN

Title (fr)

AMELIORATIONS DE DISPOSITIFS DE COMMANDE THERMIQUES

Publication

EP 0846329 B1 20000405 (EN)

Application

EP 96928535 A 19960821

Priority

- GB 9602046 W 19960821
- GB 9517094 A 19950821

Abstract (en)

[origin: WO9707319A1] Thermal controls for electric kettles and the like commonly have a bimetallic switch-operating element (108) juxtaposed in heat transfer relationship with the heating element (222) of the kettle, and a heat sink compound in grease or paste form is commonly introduced between the bimetallic element and the heating element. The heat sink compound is relatively costly and is messy and difficult to apply with precision in an automatic manufacturing process. To overcome these problems which have plagued the industry for many years, the present invention proposes to use a pad or patch of self-adhesive heat transfer tape (130) rather than the heat sink compound, such heat transfer tapes previously having been used only in the electronics industry for heat sinking of power transistors and the like.

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